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(54) **PROBE CARD**

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See application file for complete search history.

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(57) **ABSTRACT**

A probe card includes a board or silicon substrate; a plurality of probes (terminals) at a first surface of the board, the respective probes having a first extending portion extending along the first surface of the board; a plurality of through-holes formed in correspondence to the respective probes and penetrating between the first and second surfaces of the board; through electrodes embedded in the respective through-holes and conductively connected to the probes in the respective through-holes; and a wiring at the second surface of the board conductively connected to the through electrodes, the wiring having a second extending portion extending along the second surface of the board, wherein the first extending portion and the second extending portion extend in different directions from each other, and a space is formed across the entire width of the first extending portion between the first extending portion and the first surface of the board.

20 Claims, 13 Drawing Sheets

